

JOCKE		
Form 15 1-31-92	10:	Department of Commerce Patent and Trademark Office
	PATENTS ONLY	
	To the Honorable Assistant Commissioner fo original documents or	r Patents: Please record the attached copy thereof.
1.	Name of conveying party(ies):	2. Name/address of receiving Party(ies):
	Ling-Sung Wang Jyh-Ren Wu	Worldwide Semiconductor Manufacturing Corp.
	Nature of conveyance: ☑ Assignment ☐ Merger ☐ Security Agreement ☐ Other ☐ Change of Name ☐ Reassignment	No. 25, Li-Hsin Rd., Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.
4.	Date(s) of execution: January 20, 2000.	Add'1 names of receiving parties  Attached?
5.	Application number(s) or patent number(s):	09494524
	lf this documents is being filed toget execution date of the application is_ <u>J</u>	
F	A. Patent Application No. (s)	B. Patent No. (s)
	Additional numbers attached?	☐ Yes ☒ No
	Name and address of party to whom correspondence concerning document	7. Total No. of applications and patents involved:
	should be mailed:	ONE(1)  8. Total fee (37 CFR §3.41): \$40.00
	J.C. Patents, Inc. 1340 Reynolds Ave., Suite 114	Enclosed
	Irvine, CA 92614 (949) 660-0761	Charge to Acct. No.
		9. Total number of pages, including cover sheet, attachments and document 3.
-	DO NOT USE TH	IIS SPACE
10. 5	Statement and Signature:	
	To the best of my knowledge and believed and correct and any attached copy is a true.	ue copy of the original document.
	Jiawei Huang	thong 1/31/2000
	Name of Person Signing Signat	ure / Date

Registration No. 43, 330

02/25/2000 DHGUYEN 00000210 09494524 01 FC:581 (40.00 0P)

**PATENT** REEL: 010564 FRAME: 0457

## **ASSIGNMENT**

WHEREAS,

1. Ling-Sung Wang

2. Jyh-Ren Wu

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: SELF-ALIGNED FABRICATING PROCESS AND STRUCTURE OF SOURCE LINE OF ETOX FLASH MEMORY

[	] Filed:	Serial No
L	T HEG.	Ochai N

[x] Executed concurrently with the execution of this instrument

WHEREAS, Worldwide Semiconductor Manufacturing Corp.

of No. 25, Li-Hsin Rd., Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters

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## ASSIGNMENT CONTINUED

Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(is) indicated.

Signature:

Sole or First Joint Inventor: Ling-Sung Wang

Date:

Signature:

Second Joint Inventor (if any): Jyh-Ren Wu

**RECORDED: 01/31/2000** 

Date: